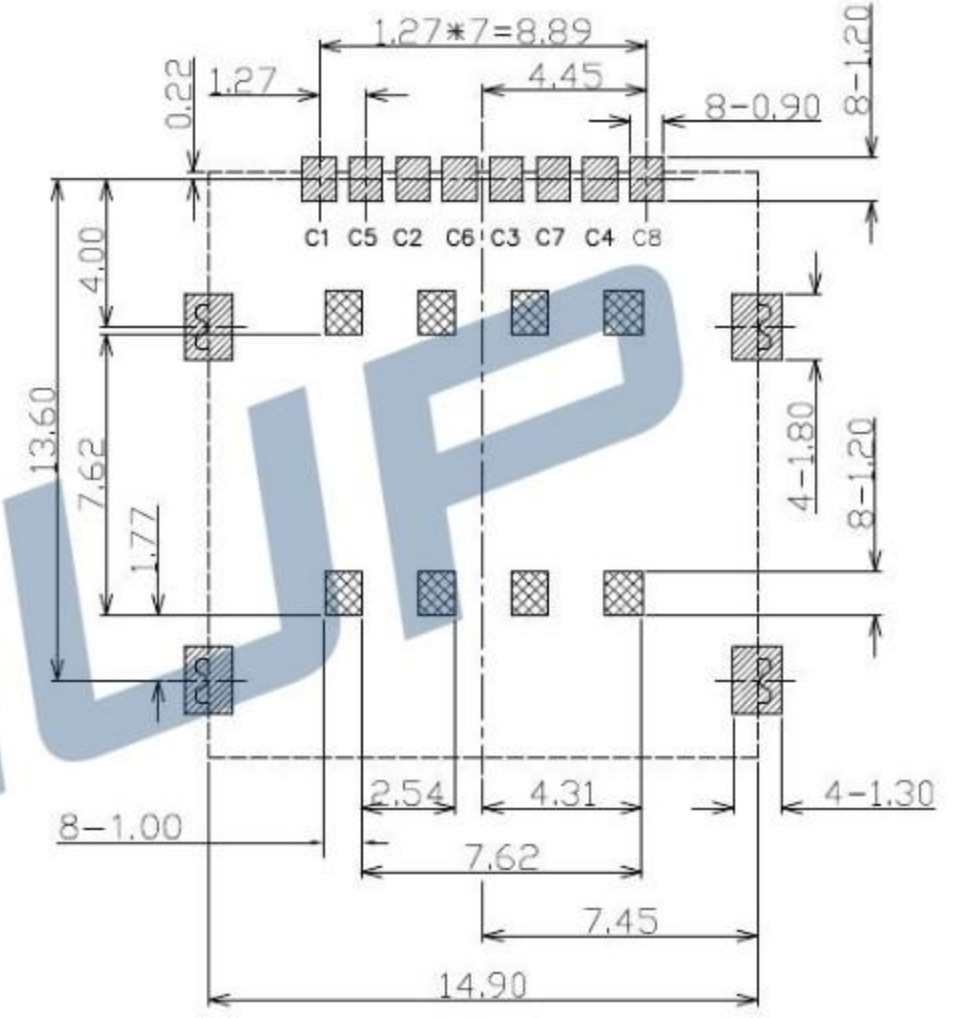
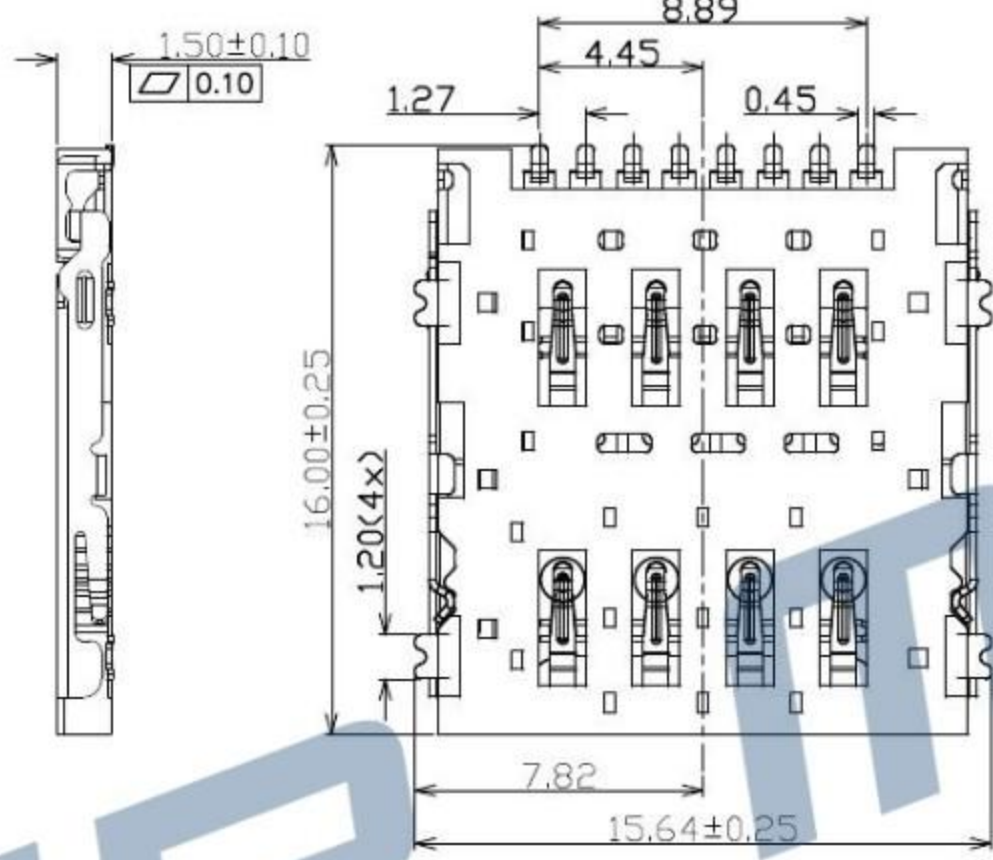
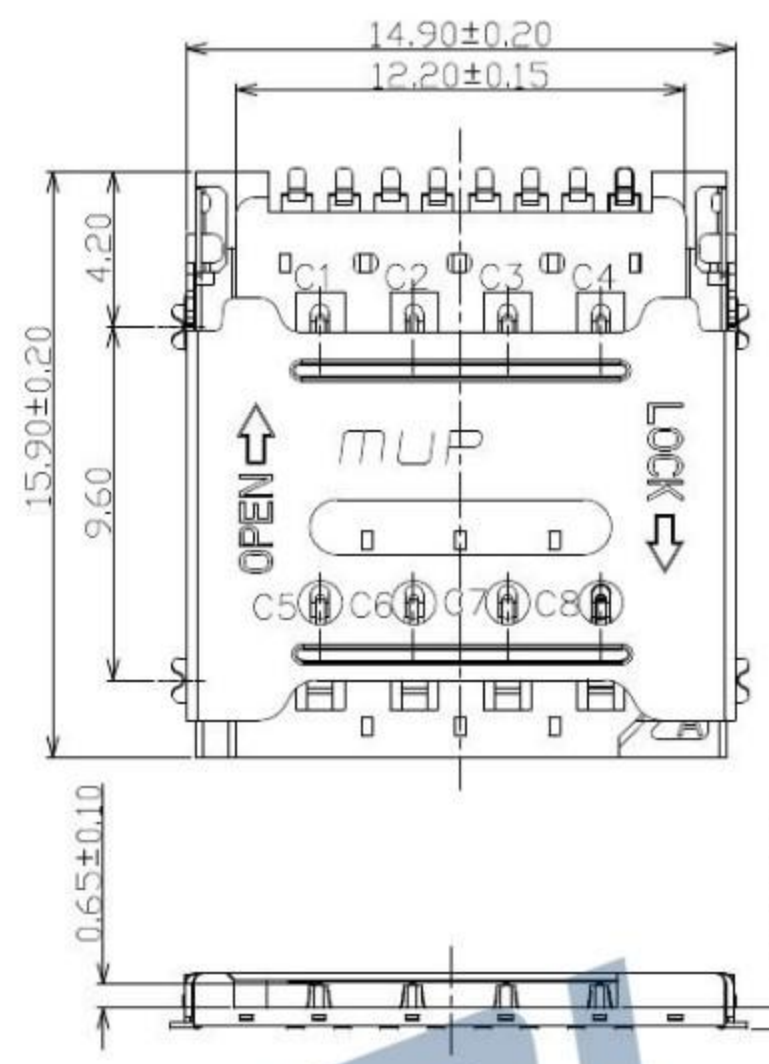


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Mar.13.2015
X2					



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- CONNECTOR OUTLINE
- NO PATTERN AND VIA HOLE IN THIS AREA

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **Micro-SIM Card Connector**

MODEL NO: **MUP-C791-3**

TYPE: **H1.50mm 8 PIN(Short shell)**

PROJ.	UNIT	SCALE	DRAWN	DWG NO.:
	mm	1:1	Henry Mar.13.2015	DWG-MUP-C791-3
CUSTOMER DRAWING			CHECKED	SHEET
			Simon Mar.13.2015	1/1
			APPROVAL	REVISION
				X1

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

**TECHNICAL CHARACTERISTICS**  
 1.General Characteristics  
 Dimensions:15.90LX14.90WX1.50H mm  
 Durability:5,000 cycles min.  
 2.Electrical Characteristics  
 Contact resistance:50mΩ typical,  
 100mΩMax  
 Insulation resistance:>1000M/500V DC  
 3.Solderability  
 Vaporphase:215°C, 30sec.Max  
 IR reflow:260°C,5sec.Max  
 Manual soldering:370°C.3sec.Max  
 4.Environmental Characteristics  
 Operating temperature:-40°C~+85°C  
 Operating humidity:10%~+95%RH

